



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



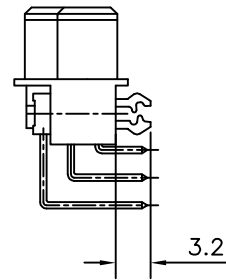
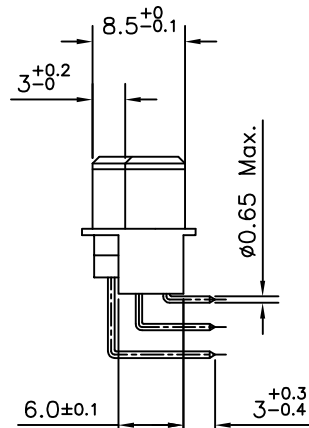
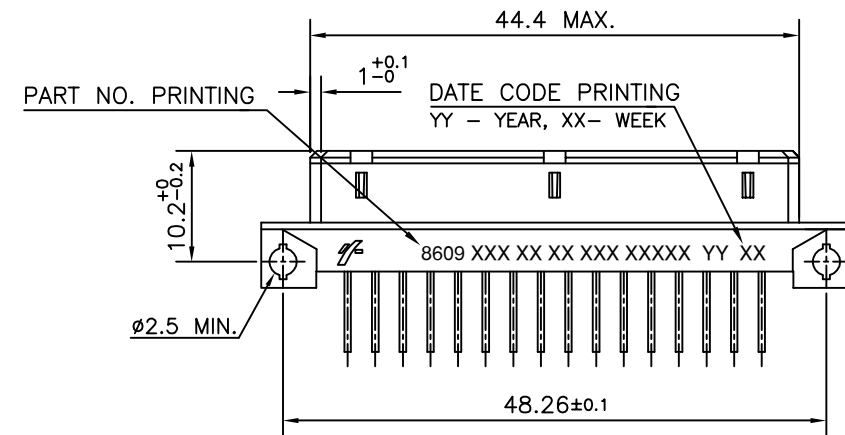
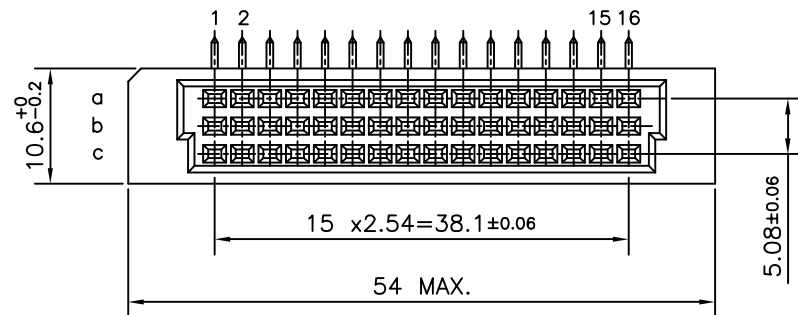
## Contact us

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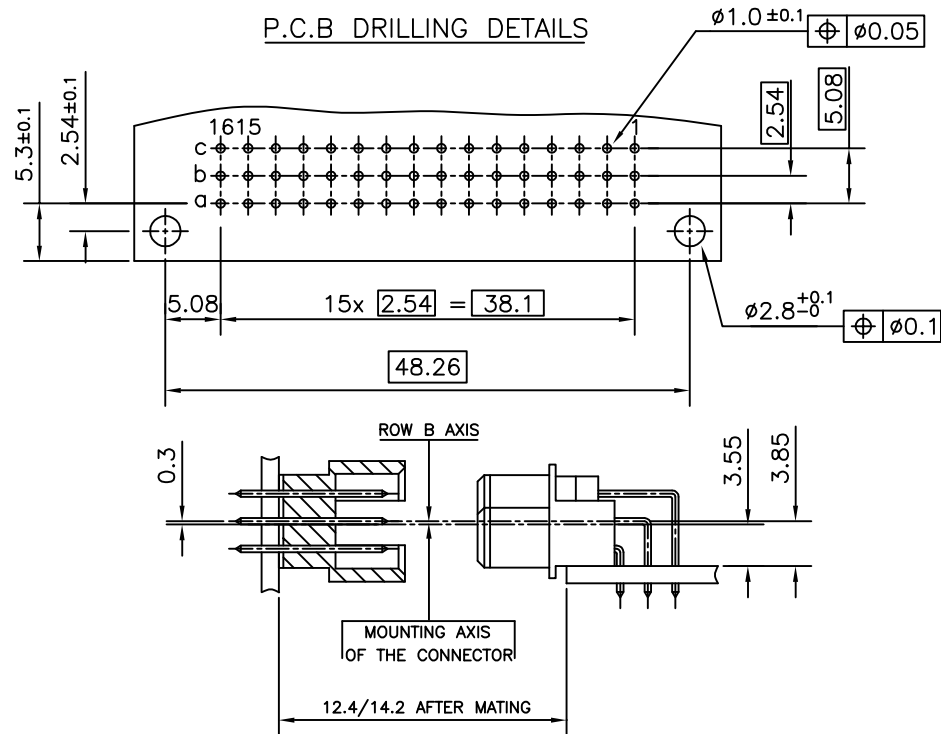




NO OPTION

WITH HARPOONS

P.C.B DRILLING DETAILS



TECHNICAL SPECIFICATION

HOUSING MATERIAL : THERMOPLASTIC POLYESTER UL 94V-0, GREY  
 HOUSING CAN WITHSTAND EXPOSURE TO LEAD FREE WAVE SOLDERING TEMPERATURE OF 260-265°C  
 WHEN USED WITH PROTECTIVE ADHESIVE OR PROTECTIVE METALLIC DEVICE FOR RIGHT ANGLE  
 CONNECTORS AS IT IS USED IN CLASSICAL LEAD WAVE SOLDERING AT 235-250°C

CONTACT MATERIAL : COPPER ALLOY  
 CONTACT PLATING :  
 ACTIVE ZONE : GOLD OVER NICKEL  
 TERMINATION ZONE :  
 TIN LEAD VERSION : TIN LEAD OVER NICKEL  
 LEAD FREE VERSION : TIN (PURE MATTE) OVER Ni  
 HARPOON PLATING :  
 TIN LEAD VERSION : TIN LEAD OVER NICKEL  
 LEAD FREE VERSION : TIN (PURE MATTE) OVER Ni

ELECTRICAL DATA

CURRENT RATING AT 20°C : 1,5 A  
 CURRENT (I MAX) : 2 A  
 TEMPERATURE RANGE : -55°C/ +125°C  
 CONTACT RESISTANCE : ≤ 20mΩ  
 INSULATION RESISTANCE : ≥ 10<sup>6</sup> MΩ  
 TEST VOLTAGE (rms) : 1000V

MECHANICAL DATA

INSERTION FORCE PER CONTACT : ≤ 0.94N  
 EXTRACTION FORCE PER CONTACT : ≥ 0.15N

REFERENCE SPECIFICATIONS : DIN 41612 / IEC 603-2

SERIES	8609	3	48	8	6	13	7	6	5	000E1
ROWS FITTED WITH CONTACTS										
Rows a b c		3	48							
Rows a - c		4	32							
NUMBER OF CONTACTS										
TYPE OF INSULATOR										
3 ROW FEMALE INSULATOR										8
METHOD OF MOUNTING										
REVERSE MOUNTING - STYLE R/2										6
TERMINATION										
ANGLED SPILL										13
OPTIONS										
NO OPTION										7
WITH HARPOONS										H
PERFORMANCE CLASS										
DIN 41612 CLASS 3										4
DIN 41612 CLASS 2										5
DIN 41612 CLASS 1										6
AS PER MIL C 55302/ JSS 50808										8
PITCH PER ROW										
2.54										5
000E1										TIN LEAD VERSION
E1LF										LEAD FREE VERSION

NOTES:-  
 1. THE "LF" PRODUCTS MEET EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008  
 2. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 3.5 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.6 MM MINIMUM THICK CIRCUIT BOARD  
 3. LEAD FREE OR RoHS DIRECTIVE LABELING TO BE PROVIDED AS PER GS-14-920 FOR LEAD FREE VERSION.

mat'l. code		surface		tolerance		projection		product family	
-		ISO 1302		ISO 406 ISO 1101		mm		8609	
ltr		ecn no		dr		date		title	
A		I04-0100		MINI		09/11/2004		DIN REVERSE RECEPTACLE	
B		I05-0042		MINI		19/05/2005		ANGLED SPILL DIN 41612 STYLE- R/ 2	
C		I06-0063		MINI		01/06/2006		scale -	
sheet index		revision		C		sheet		1	